ABSTRACT

A multi-package module comprises a plurality of stacked packages including an upper package and a lower package. Each package comprises a board having located on a first side thereof a chip installation area and a bump pad area; at least one chip disposed in the chip installation area; a plurality of redistribution patterns formed on the board and electrically connected to the chip; and a plurality of first bump pads formed in the bump pad area which are electrically connected to the redistribution patterns. The respective packages are electrically connected by connecting bump pads of the upper package to bump pads of the lower package. Further, the chip installation area of the upper and lower packages not being in vertical alignment with each other.